



Subject: PFAS (Per- and polyfluoroalkyl substances) Inquiry

Product(s): HD8820

This information is being provided to assist our customers and their value chain with regulatory compliance obligations in various regions of the world.

HD8820 is a PBO polymer precursor solution designed for the creation of insulating layers on semiconductor devices. The relevant HTS code is 3707.90.3290. HD MicroSystems intentionally includes two C1 PFAS substances in the formulation of HD8820.

- The first (a polymer), Benzoyl chloride, 4,4'-oxybis-, polymer with 3-aminophenol and 4,4'-[2,2,2-trifluoro-1-(trifluoromethyl)ethylidene]bis[2-aminophenophenol], is identified by CAS 895581-94-9, and has an EC number of 467-870-5.
- The second, 5,5'-(trifluoro-1-(trifluoromethyl)ethylidene)bis(2-hydroxy-1,3-benzenedimethanol), is identified by CAS 441768-78-1 and does not have a known EC number.

The first substance, a PBO polymer precursor resin, is present in our formulation at 30-40%, and the second substance, a crosslinker, at 0.5-2.5%. Both of these substances are expected to react during curing at customer sites and form covalent bonds to other substances present during the curing process. HDM does not have knowledge of the final fluorinated substances present in films cured by HDM customers.

To date, there are no known regulatory restrictions which prevent our customers' use of HDM products in their intended applications worldwide.

We value your business and remain committed to delivering innovative and sustainable products to you today and in the future.

Yours Sincerely,

Supplier Name: HD MicroSystems LLC

Authorized Name: Matthew A Taylor, PhD, DABT

Title: PS&R Substances of Concern/Toxicology Leader

Date: 20 July 2026